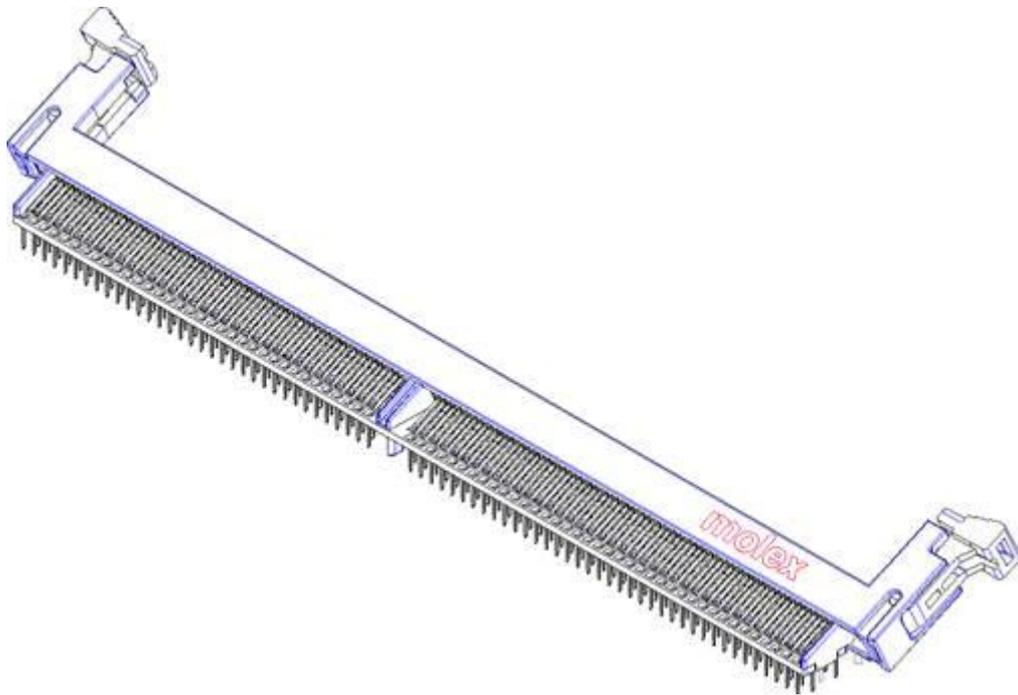




TEST SUMMARY

SIGNAL INTEGRITY TEST SUMMARY

DDR4 DIMM 0.85MM PITCH 25 DEGREES CONNECTOR



1.0 SCOPE

This test summary covers the signal integrity performance of DDR4 DIMM 0.85mm Pitch 25 Degrees through-hole connector. The measurement was conducted using Molex DDR4 Angled 25 Degrees test fixture. Most of the test fixture effect was removed using AFR in PLTS.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND PART NUMBER

DDR4 DIMM 0.85mm Pitch 25 Degrees through-hole connector, Part # 151080-0101.

REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 1 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

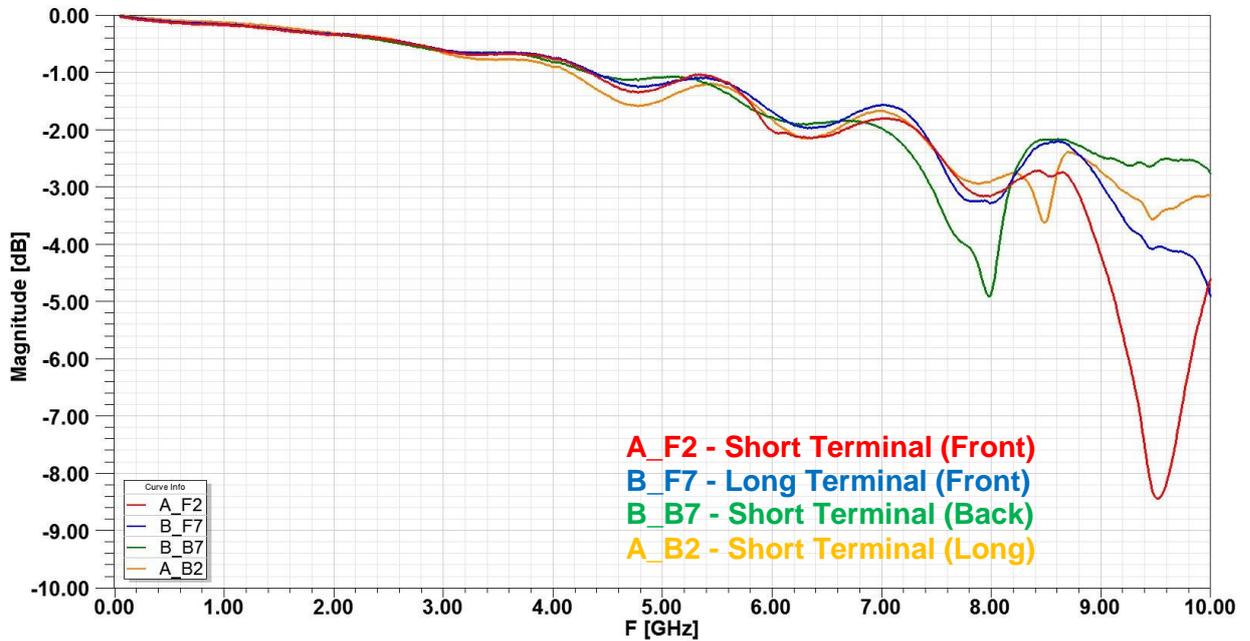


TEST SUMMARY

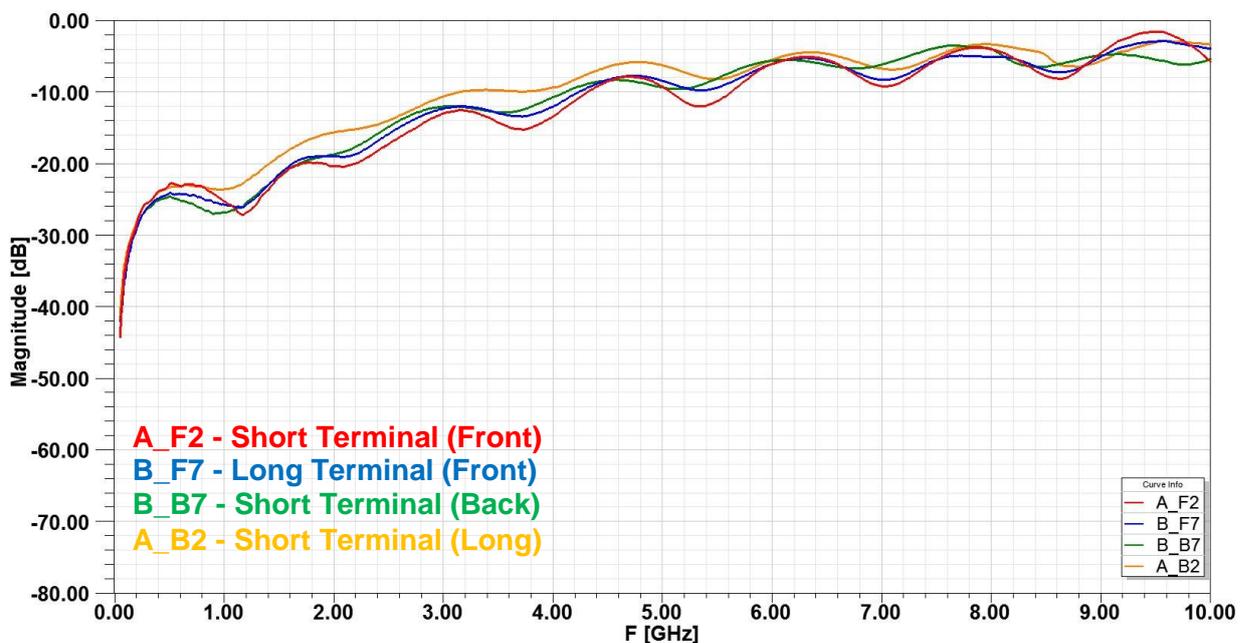
3.0 PERFORMANCE

Frequency Domain

Insertion Loss



Return Loss



REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 2 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

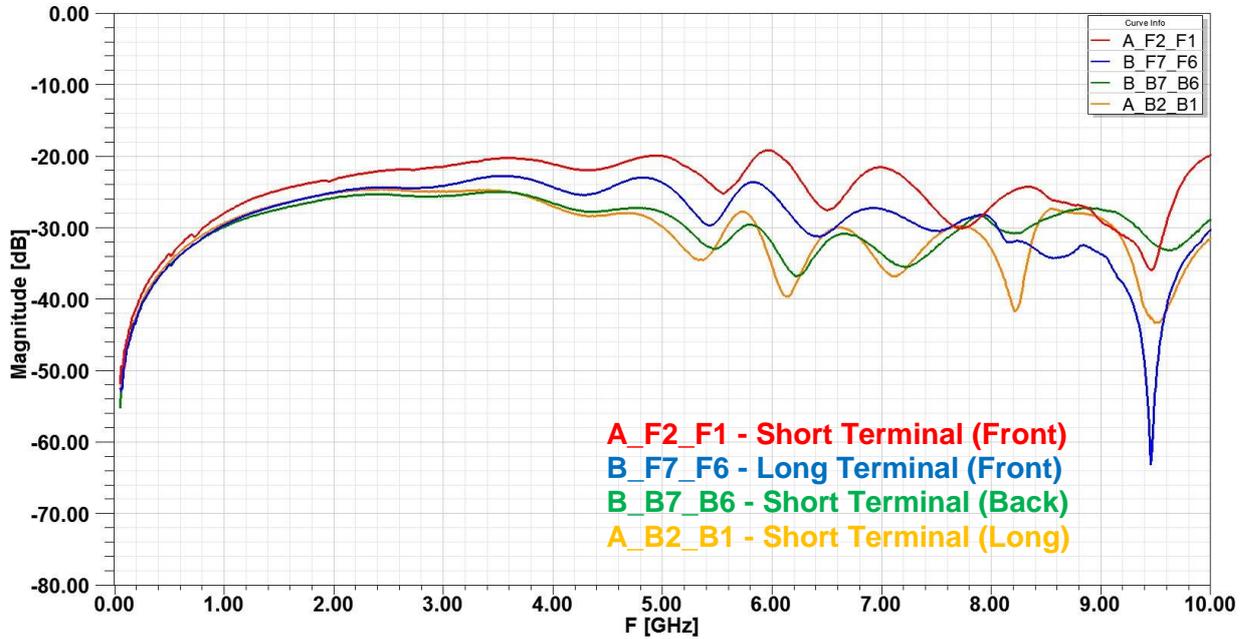


TEST SUMMARY

Frequency Domain (continued)

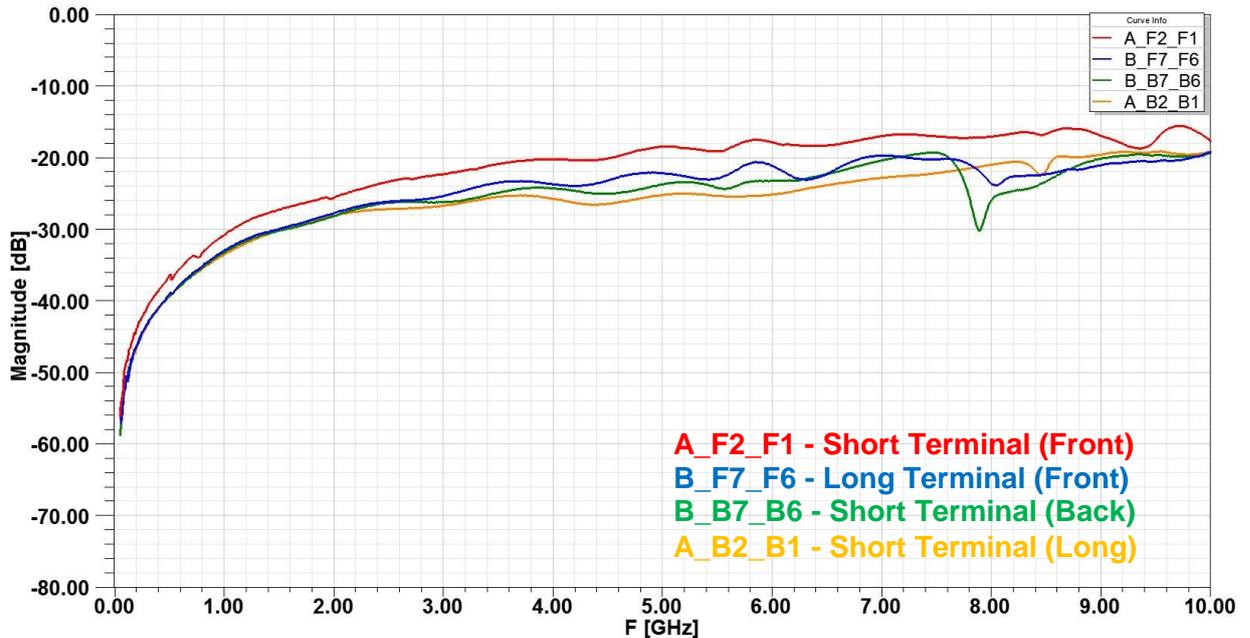
Near End Cross-Talk (Same Side)

- 1:1 S/G ratio
- Both victim and aggressor located at same row



Far End Cross-Talk (Same Side)

- 1:1 S/G ratio
- Both victim and aggressor located at same row



REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 3 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

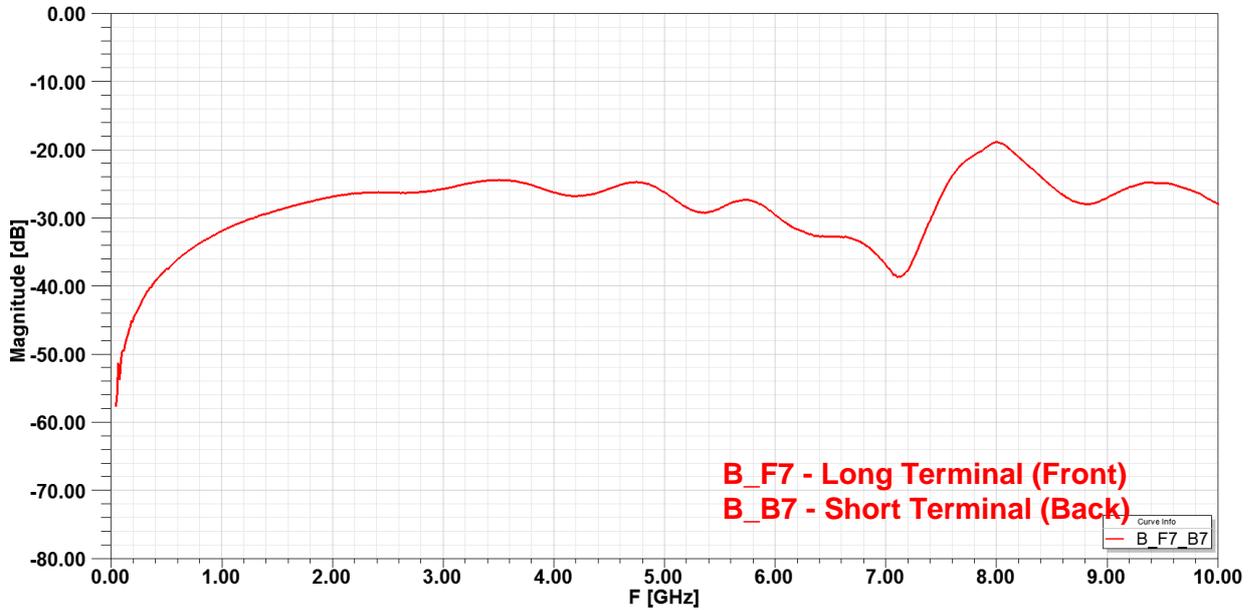


TEST SUMMARY

Frequency Domain (continued)

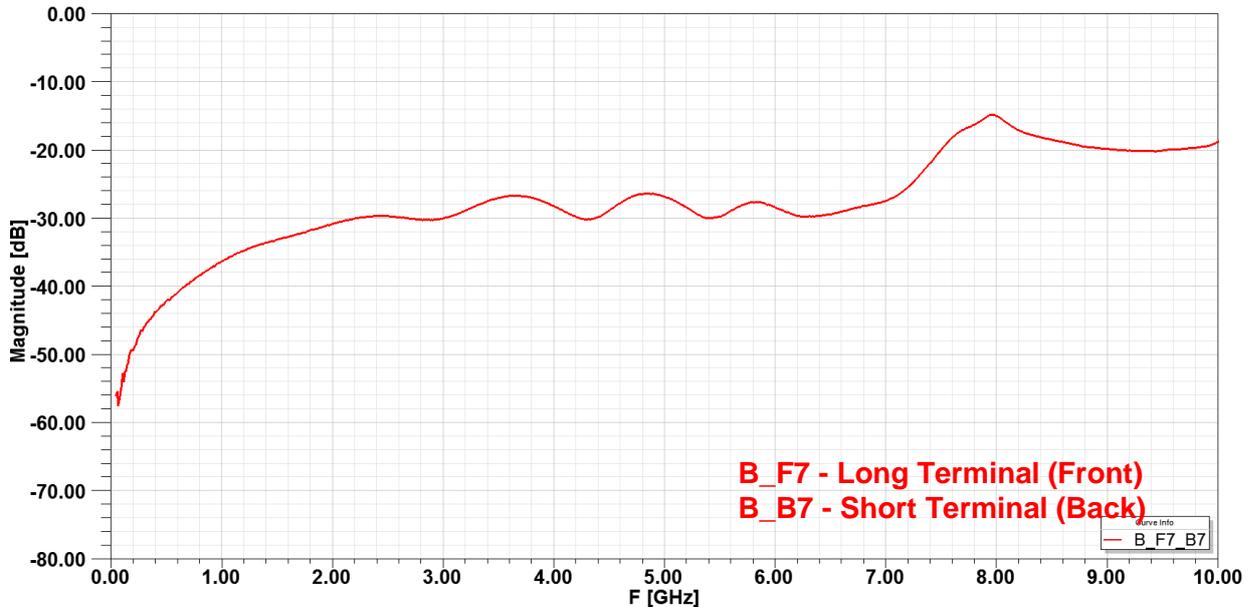
Near End Cross-Talk (Opposite Side)

- 1:1 S/G ratio
- Victim locates at inner row from front side
- Aggressor locates at inner row from back side



Far End Cross-Talk (Opposite Side)

- 1:1 S/G ratio
- Victim locates at inner row from front side
- Aggressor locates at inner row from back side.
-



REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 4 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

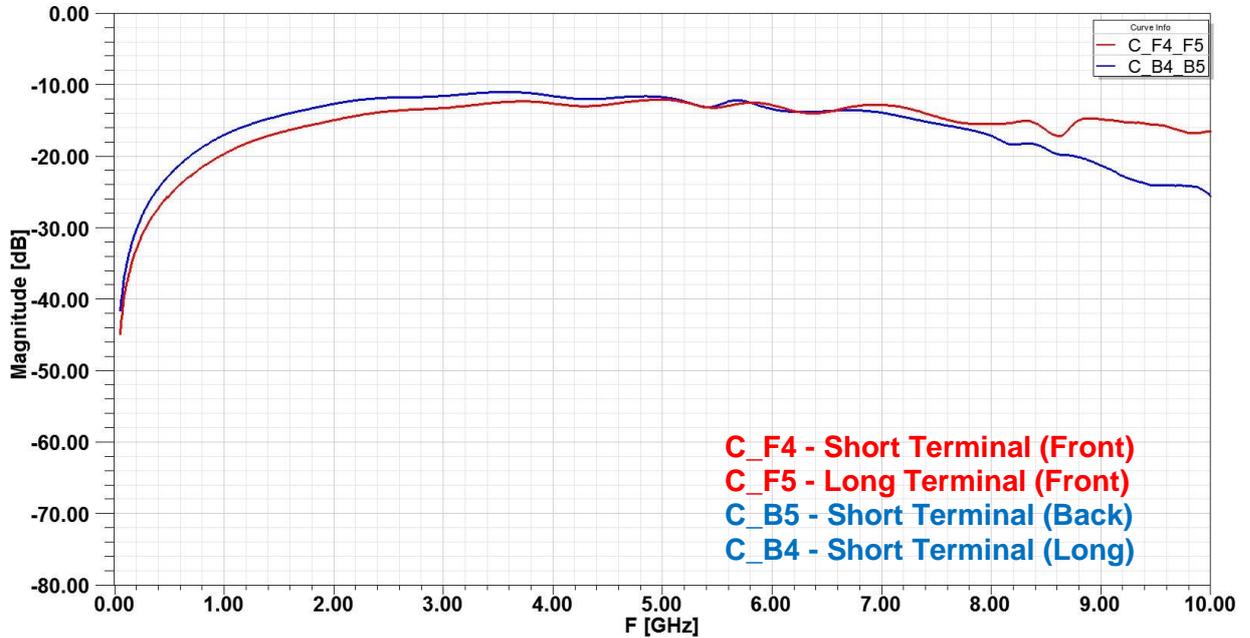


TEST SUMMARY

Frequency Domain (continued)

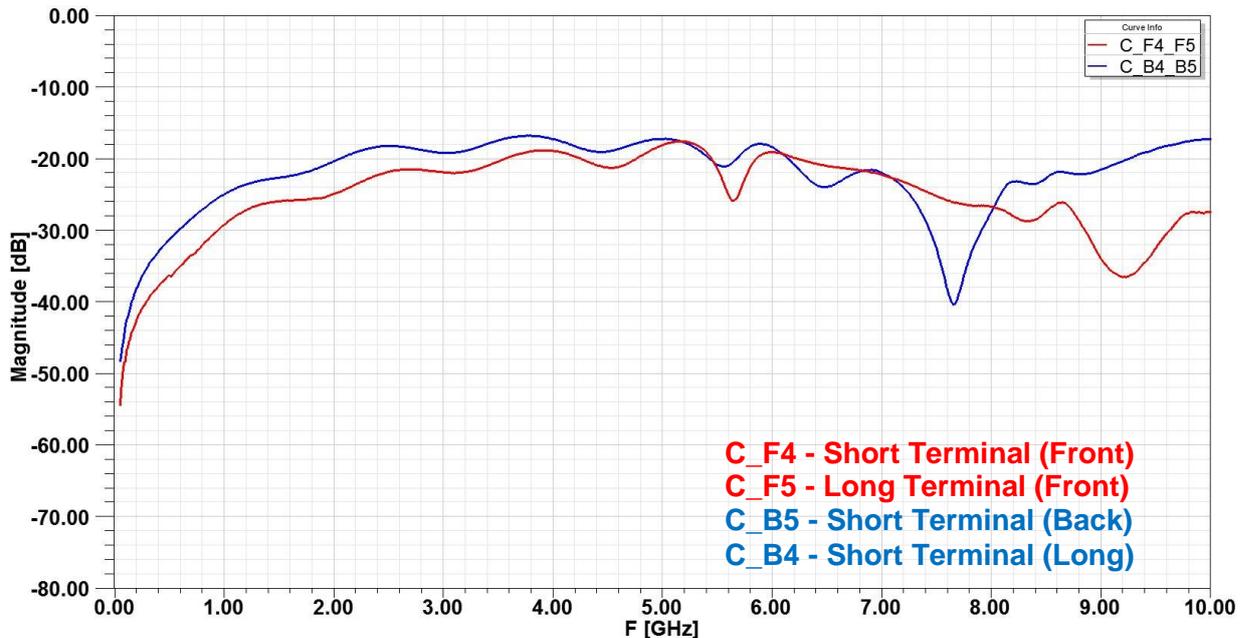
Near End Cross-Talk (Same Side)

- 2:1 S/G ratio



Far End Cross-Talk (Same Side)

- 2:1 S/G ratio



REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 5 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

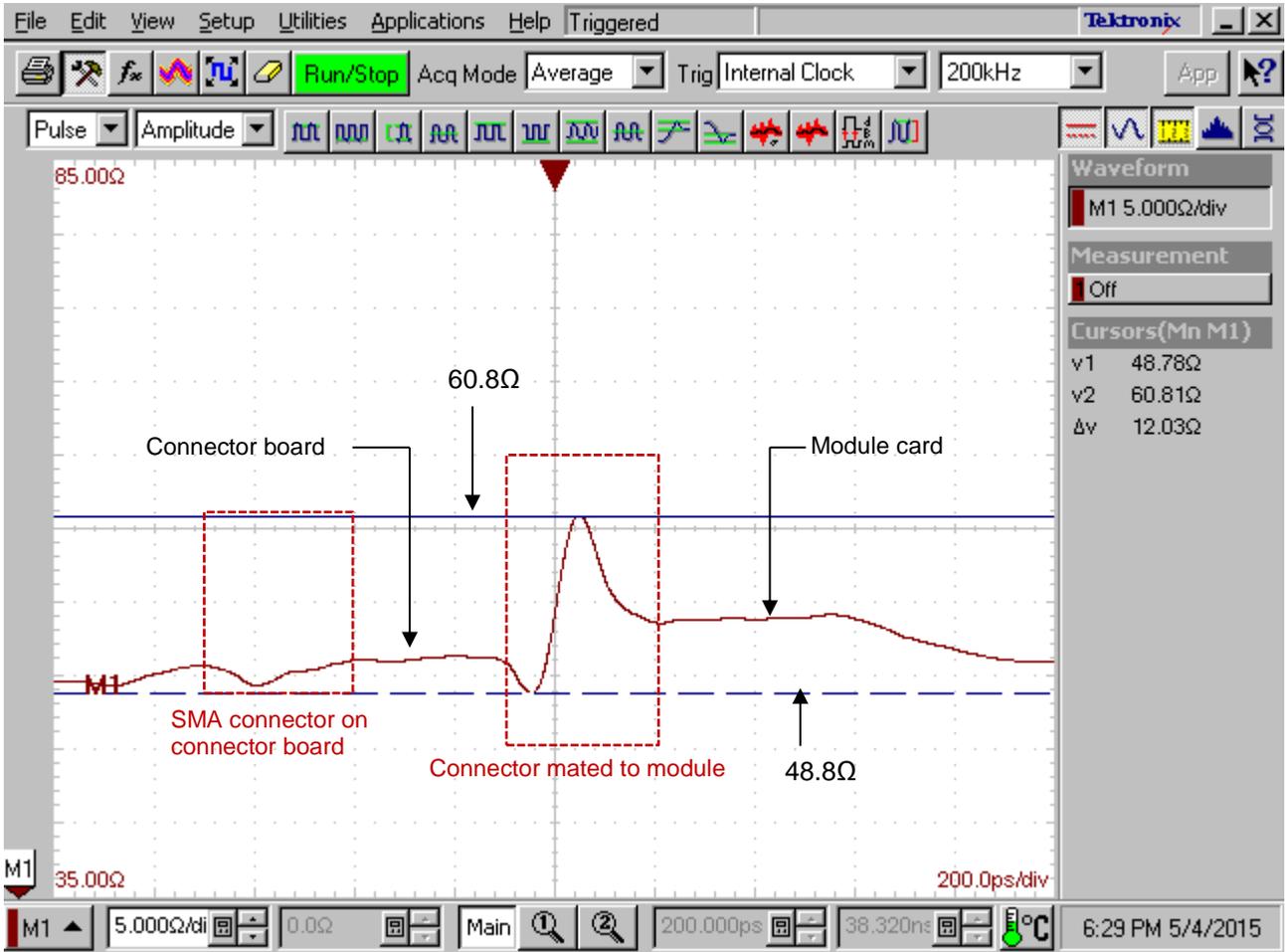


TEST SUMMARY

Time Domain

TDR Impedance

- A_F2 – Short terminal (Front)
- Referenced rise-time of 100ps [10%~90%] launched at connector footprint

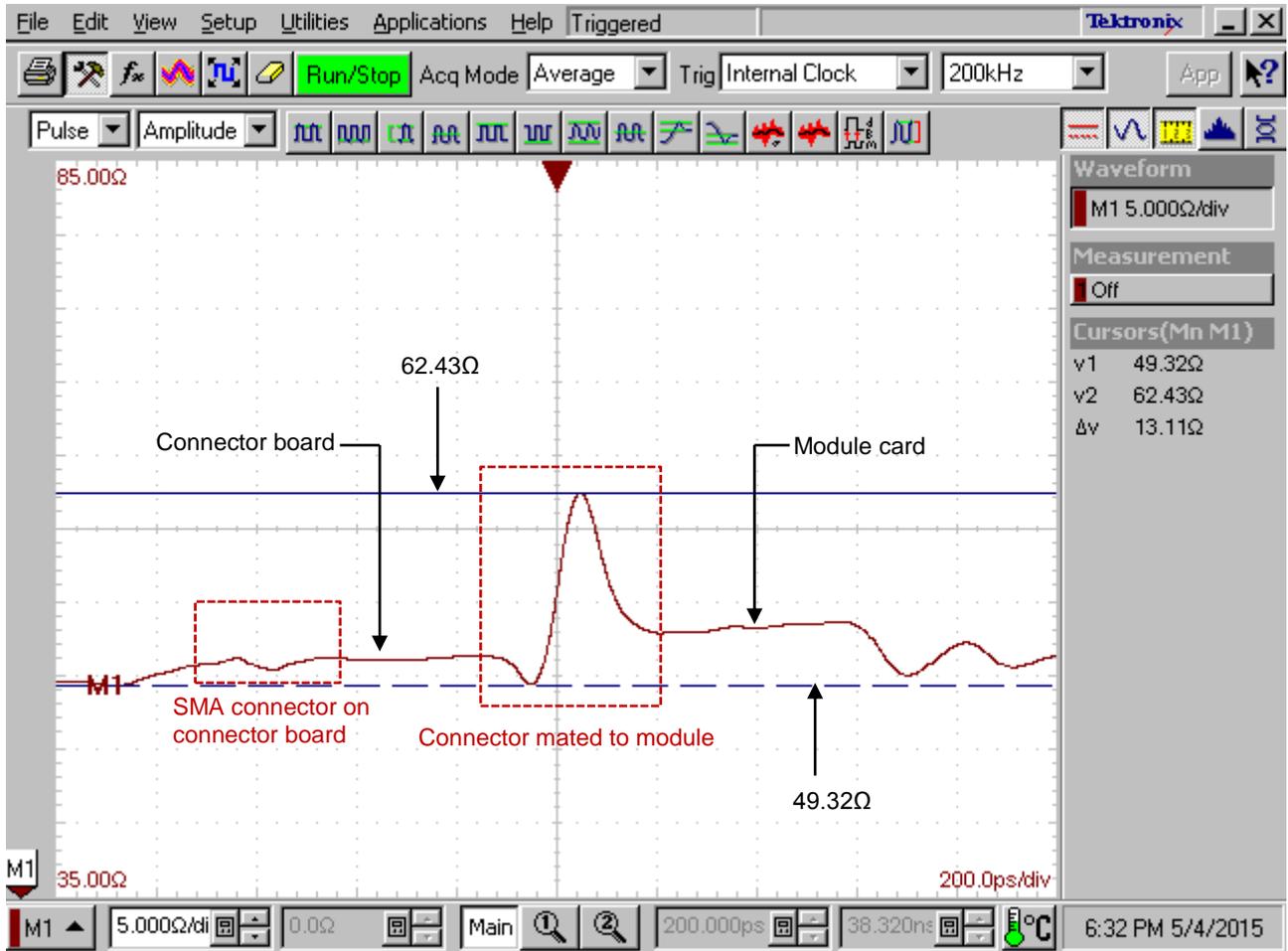


REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 6 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

Time Domain (continued)

TDR Impedance

- B_F7 – Long terminal (Front)
- Referenced rise-time of 100ps [10%~90%] launched at connector footprint



REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 7 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

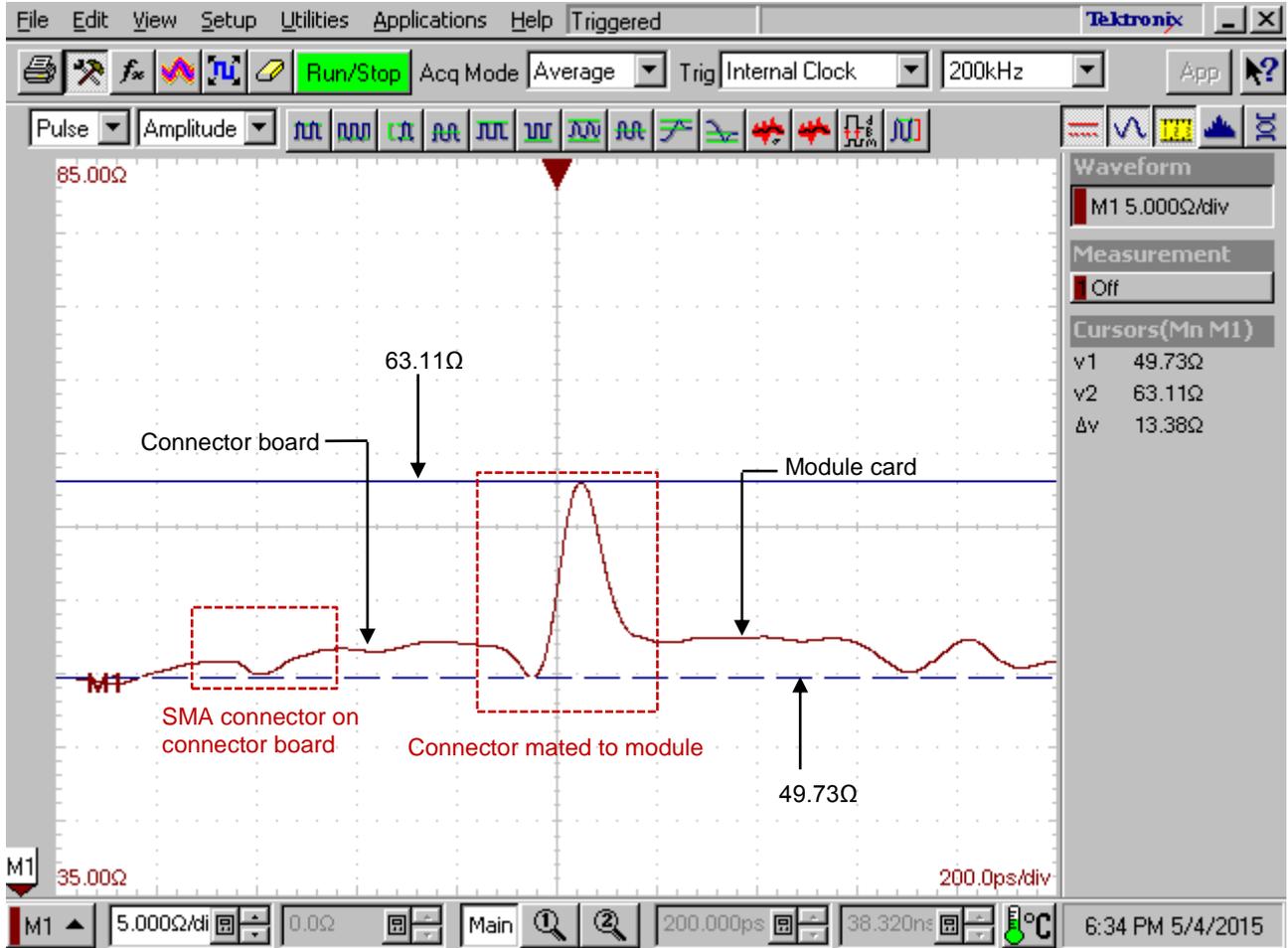


TEST SUMMARY

Time Domain (continued)

TDR Impedance

- B_B7 – Short terminal (Back)
- Referenced rise-time of 100ps [10%~90%] launched at connector footprint



REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 8 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

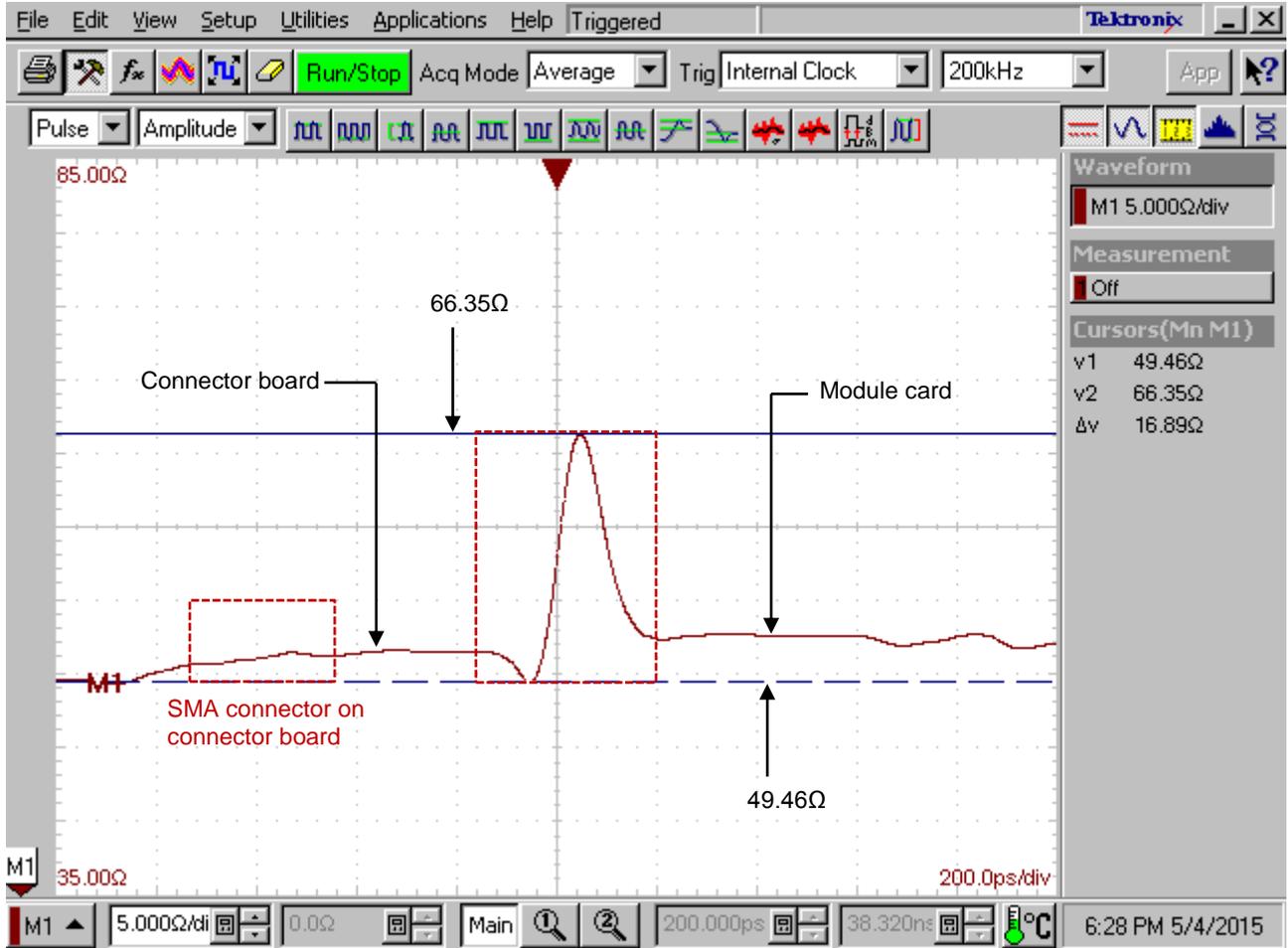


TEST SUMMARY

Time Domain (continued)

TDR Impedance (A_B2)

- A_B2 – Long terminal (Back)
- Referenced rise-time of 100ps [10%~90%] launched at connector footprint



REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 9 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22



TEST SUMMARY

4.0 TEST FIXTURES



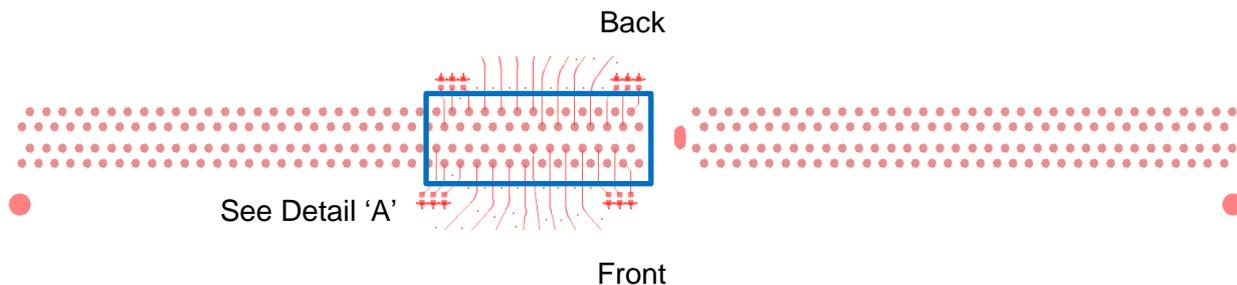
Molex DDR4 Test Fixture Board Information

Material : TU-872-SLK
 Thickness : 1.4mm
 High Speed Traces : High-Speed Signals on Top Layer (referenced to Layer 2) and Bottom Layer (referenced to Layer 3)
 0.09398mm dielectric thickness between Top Layer & Layer 2 ; Layer 3 & Bottom Layer
 50.8mm single-ended length (both main and module board)

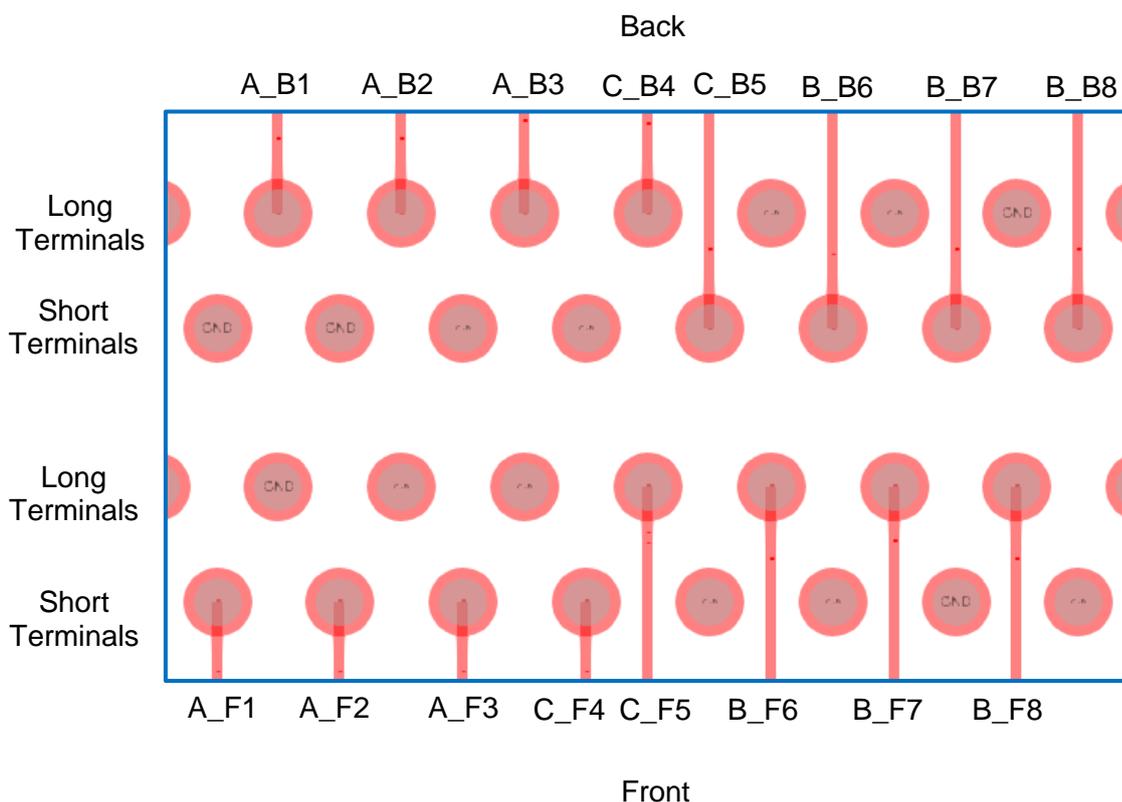
REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 10 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22

TEST SUMMARY

Mainboard Footprint Detail



Detail 'A'



REVISION: B	ECN INFORMATION: EC No: S2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL	SHEET No. 11 of 11
DOCUMENT NUMBER: TS-151080-0001	CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPROVED BY: WTCHUA 2015/05/22